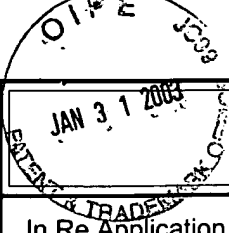
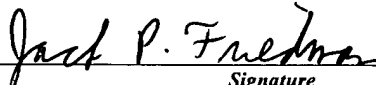
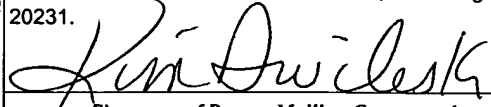


2823

 TRANSMITTAL LETTER (General - Patent Pending)		Docket No. END920010026US1	
In Re Application Of: Bernier et al.			
Serial No. 09/885,853	Filing Date 6/20/2001	Examiner William D. Coleman	Group Art Unit 2823
Title: EXTENSION OF FATIGUE LIFE FOR C4 SOLDER BALL TO CHIP CONNECTION			
<u>TO THE ASSISTANT COMMISSIONER FOR PATENTS:</u>			
Transmitted herewith is: Amendment			
in the above identified application.			
<input checked="" type="checkbox"/> No additional fee is required. <input type="checkbox"/> A check in the amount of _____ is attached. <input checked="" type="checkbox"/> The Assistant Commissioner is hereby authorized to charge and credit Deposit Account No. 09-0457(IBM) as described below. A duplicate copy of this sheet is enclosed.			
<input type="checkbox"/> Charge the amount of _____ <input checked="" type="checkbox"/> Credit any overpayment. <input checked="" type="checkbox"/> Charge any additional fee required.			
 _____ <i>Signature</i>		Dated: 1/28/2003	
Jack P. Friedman Reg. No. 44,688 Schmeiser, Olsen & Watts 3 Lear Jet Lane, Suite 201 Latham, NY 12110 (518) 220-1850		<div style="border: 1px solid black; padding: 5px;"> I certify that this document and fee is being deposited on 1/28/2003 with the U.S. Postal Service as first class mail under 37 C.F.R. 1.8 and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.  _____ <i>Signature of Person Mailing Correspondence</i> Kim Dwileski _____ <i>Typed or Printed Name of Person Mailing Correspondence</i> </div>	
CC:			

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Bernier *et al.*

Art Unit: 2823

Serial No.: 09/885,853 ✓

Dkt. No.: END920010026US1

Filed: 6/20/01 ✓

Examiner: William D. Coleman

Title: **EXTENSION OF FATIGUE LIFE FOR C4 SOLDER BALL TO CHIP CONNECTION**

Commissioner for Patents
Washington, DC 20231

Sir:

This paper is being filed in response to a Office Action dated November 8, 2002 in connection with the above-identified application. Reconsideration and allowance are respectfully requested in view of the Amendments and Remarks below.

Amendment

In the Claims

✓
Please cancel claim 19. No claims are amended herein in the present office action response. Currently pending claims 1-6, 9-18, and 20 for consideration by the Examiner are as follows:

1. An electronic structure, comprising:

a semiconductor substrate having a first electrically conductive pad thereon;

an organic substrate having a second electrically conductive pad thereon, wherein a

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